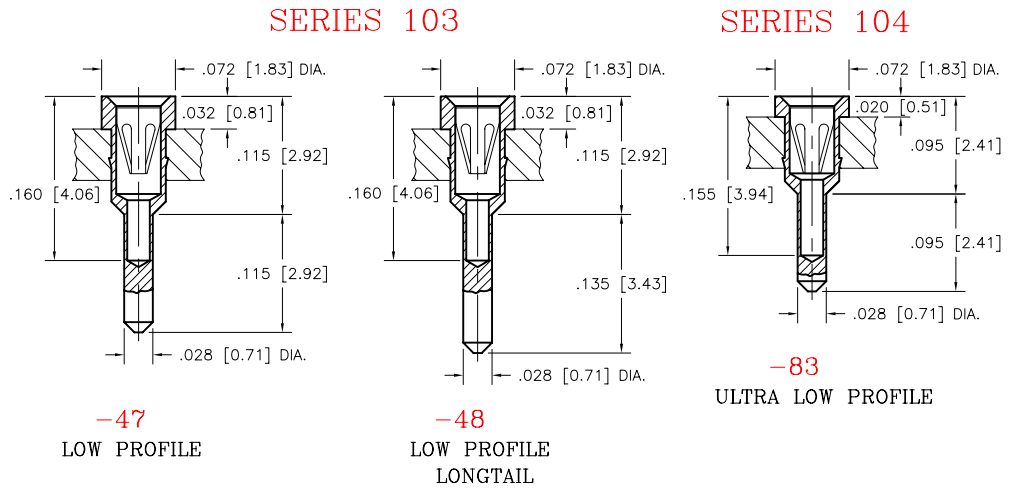
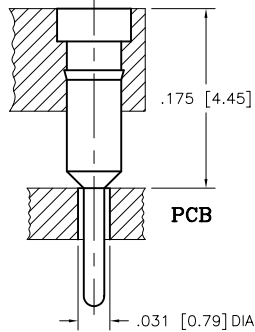
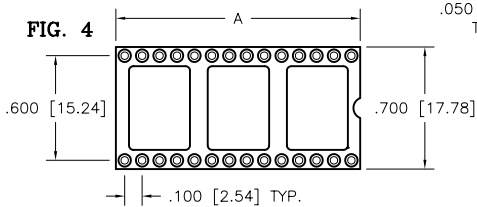
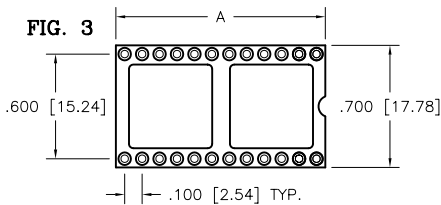
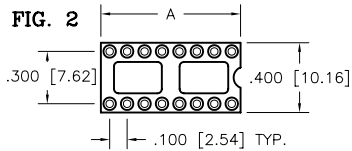
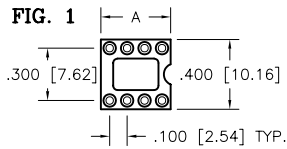


**SERIES 103** LOW PROFILE DIP SOCKET (OPEN FRAME)  
**SERIES 104** ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME)  
**SERIES 105** ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME WITHOUT CROSSBARS)

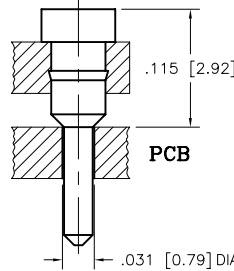
WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	24	1.200 [30.48]	624
	28	1.400 [35.56]	628
FIG. 4	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640



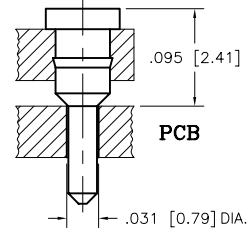
STANDARD HEIGHT ABOVE PCB WITH -01 TERMINAL



34% REDUCED HEIGHT WITH -47 TERMINAL



46% REDUCED HEIGHT WITH -83 TERMINAL



**CONTACT TYPE**

<b>S: STANDARD DIP</b>	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
<b>M: STANDARD PGA</b>	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
<b>L: INTERSTITIAL PGA</b>	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
<b>H: HIGH FORCE</b>	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

**TECHNICAL SPECIFICATIONS**

**MATERIAL**  
**INSULATOR** GLASS FILLED POLYESTER  
 UL 94V-0 LISTED  
**TERMINAL** BRASS PER ASTM-B16  
**CONTACT** BeCu PER ASTM-B194  
**OPERATING TEMP.** -65°C TO +125°C

**CONTACT FORCES**  
**INSERTION** STANDARD 9 oz. AVG.  
**WITHDRAWAL** STANDARD 2 oz. MIN.

**ORDERING INFORMATION**

